



Material Content Data Sheet



Sales Product Name		BTS5016-2EKA		Issued		29. August 2013		
MA#		MA001072466						
Package		PG-DSO-14-40		Weight*		150.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.723	3.14	3.14	31398	31398
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		463	
	non noble metal	iron	7439-89-6	1.392	0.93		9252	
wire	non noble metal	copper	7440-50-8	56.512	37.57	38.56	375656	385487
	non noble metal	copper	7440-50-8	1.345	0.89	0.89	8940	8940
	organic material	carbon black	1333-86-4	0.165	0.11		1096	
encapsulation	plastics	epoxy resin	-	7.584	5.04		50412	
	inorganic material	silicondioxide	60676-86-0	74.683	49.64	54.79	496449	547957
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8151	8151
plating	noble metal	silver	7440-22-4	1.417	0.94	0.94	9423	9423
glue	plastics	epoxy resin	-	0.228	0.15		1513	
	noble metal	silver	7440-22-4	1.073	0.71	0.86	7131	8644
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com